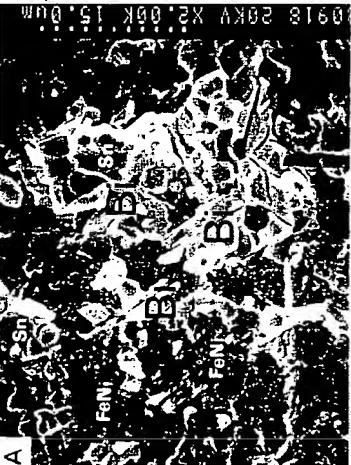


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Lead Metallization	Sn-1Bi Thickness: 10μm	Sn-2Bi/Sn Thickness: 4/6μm
		
Lead Side		
Substrate Electrode Side		
Bi distribution		Heterogeneous

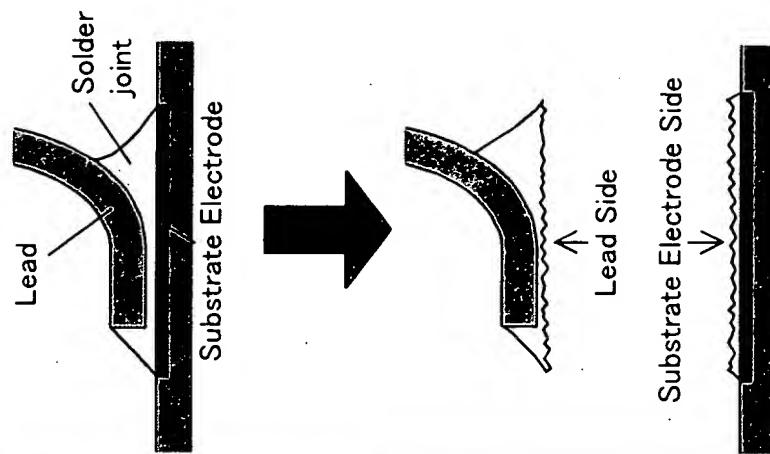


Figure 1 Fracture surface of solder joint (1)

Solder: Sn-2.8Ag-15Bi Lead: 42 Alloy